

# Copper Bath SLOTOCOUP HL 10 for horizontal reel-to-reel plating lines with insoluble anodes

Copper Bath SLOTOCOUP HL 10 is used for plating of printed circuit boards in horizontal reel-to-reel plating lines with insoluble anodes. It is especially suitable for periodic current reverse (reverse pulse plating).

Copper Bath SLOTOCOUP HL 10 deposits fine grained, ductile coatings with excellent metal distribution. Make-up and operation of the electrolyte is carried out with two additives.

Operating the Copper Bath SLOTOCOUP HL 10 with periodic reverse pulse plating may shorten the plating time significantly with an excellent metal distribution at the same time.

Copper Bath SLOTOCOUP HL 10 can also be operated with direct current (Direct Current Plating) and then provides bright, fine grained and ductile copper deposits.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

#### Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at [www.schloetter.com/downloads](http://www.schloetter.com/downloads).

For the storage of chemical products the TRGS 510 must be followed.

**If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.**

